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### INTEGRATED CIRCUITS



Product data Supersedes data of 1990 Mar 01 2003 Feb 05



Philips Semiconductors

#### 74F299

#### **FEATURES**

- Common parallel I/O for reduced pin count
- Additional serial inputs and outputs for expansion
- Four operating modes: Shift left, shift right, load and store
- 3-State outputs for bus-oriented applications

#### DESCRIPTION

The 74F299 is an 8-bit universal shift/storage register with 3-State outputs. Four modes of operation are possible: Hold (store), shift left, shift right and parallel load. The parallel load inputs and flip-flop outputs are multiplexed to reduce the total number of package pins. Additional outputs are provided for flip-flops Q0 and Q7 to allow easy serial cascading. A separate active-LOW Master Reset is used to reset the register.

The 74F299 contains eight edge-triggered D-type flip-flops and the interstage logic necessary to perform synchronous shift left, shift right, parallel load and hold operations. The type of operation is determined by S0 and S1, as shown in the Function Table. All flip-flop outputs are brought out through 3-State buffers to separate I/O pins that also serve as data inputs in the parallel load mode. Q0 and Q7 are also brought out on other pins for expansion in serial shifting of longer words.

A LOW signal on  $\overline{\text{MR}}$  overrides the Select and CP inputs and resets the flip-flops. All other state changes are initiated by the rising edge of the clock. Inputs can change when the clock is in either state provided only that the recommended set-up and hold times, relative to the rising edge of clock are observed.

A HIGH signal on either  $\overline{OE0}$  or  $\overline{OE1}$  disables the 3-State buffers and puts the I/O pins in the high impedance state. In this condition the shift, hold, load and reset operations can still occur. The 3-State buffers are also disabled by High signals on both S0 and S1 in preparation for a parallel load operation.

#### INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

S0 1	20 V <sub>CC</sub>
OE0 2	19 S1
OE1 3	18 DS7
I/O6 4	17 Q7
I/O4 5	16 I/O7
I/O2 6	15 I/O5
I/O0 7	14 I/O3
Q0 8	13 I/O1
MR 9	12 CP
GND 10	11 DS0

TYPE	TYPICAL f <sub>MAX</sub>	TYPICAL SUPPLY CURRENT (TOTAL)
74F299	115 MHz	58 mA

SF00865

#### **ORDERING INFORMATION**

**PIN CONFIGURATION** 

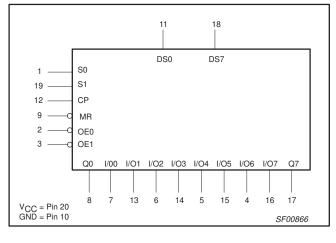
	ORDER CODE		
DESCRIPTION	COMMERCIAL RANGE V <sub>CC</sub> = 5 V ±10%, T <sub>amb</sub> = 0 °C to +70 °C	PKG DWG #	
20-pin plastic DIP	N74F299N	SOT146-1	
20-pin plastic SOL	N74F299D	SOT163-1	

PINS	DESCRIPTION	74F(U.L.) HIGH / LOW	LOAD VALUE HIGH / LOW
DS0	Serial data input for right shift	1.0 / 1.0	20 µA / 0.6 mA
DS7	Serial data input for left shift	1.0 / 1.0	20 µA / 0.6 mA
S0, S1	Mode select inputs	1.0 / 2.0	20 μA / 1.2 mA
CP	Clock pulse input (Active rising edge)	1.0 / 1.0	20 µA / 0.6 mA
MR	Asynchronous Master Reset input (Active LOW)	1.0 / 1.0	20 µA / 0.6 mA
OE0, OE1	Output Enable input (Active LOW)	1.0 / 1.0	20 µA / 0.6 mA
Q0, Q7	Serial outputs	50 / 33	1.0 mA / 20 mA
I/On	Multiplexed parallel data inputs	3.5 / 1.0	70 μA / 0.6 mA
1/011	3-State parallel outputs	150 / 40	3.0 mA / 24 mA

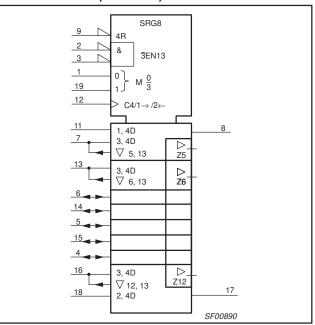
NOTE: One (1.0) FAST Unit Load (U.L.) is defined as: 20  $\mu$ A in the HIGH State and 0.6 mA in the LOW state.

### 74F299

LOGIC SYMBOL



#### LOGIC SYMBOL (IEEE/IEC)



#### **FUNCTION TABLE**

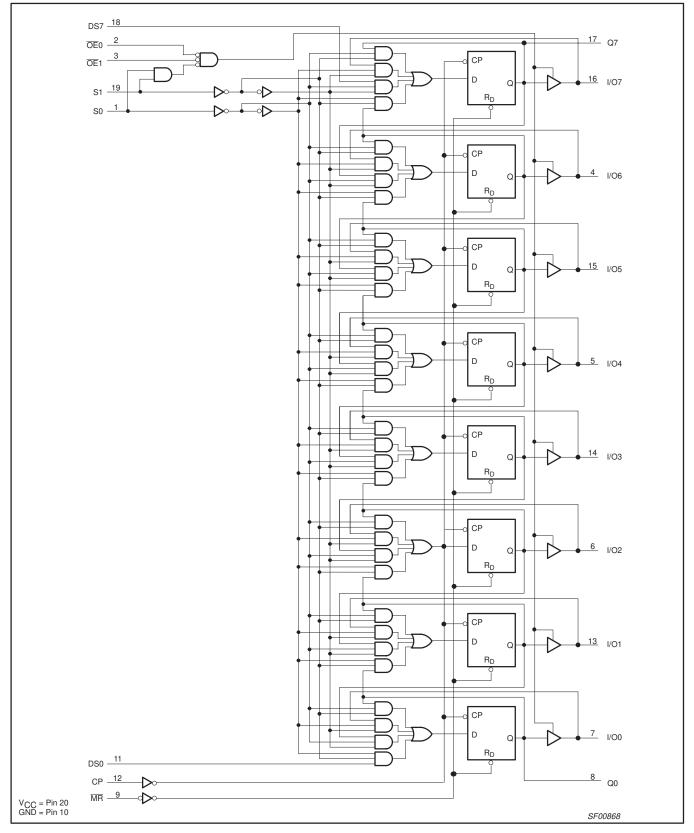
INPUTS		INP	UTS		
OEn	MR	S1	S0	СР	- OPERATING MODE
L	L	Х	Х	Х	Asynchronous Reset; Q0 – Q7 = LOW
L	Н	Н	Н	Ŷ	Parallel load; I/On $\rightarrow$ Qn (I/On outputs disabled)
L	Н	L	Н	Ŷ	Shift right; DS0 $\rightarrow$ Q0, Q0 $\rightarrow$ Q1, etc.
L	Н	Н	L	Ŷ	Shift left; DS7 $\rightarrow$ Q7, Q7 $\rightarrow$ Q6, etc.
L	Н	L	L	Х	Hold
Н	Х	Х	Х	Х	Outputs in High-Z

H = HIGH voltage level

= LOW voltage level L

X = Don't care  $\uparrow = LOW-to-HIGH clock transition$ 

#### LOGIC DIAGRAM



74F299

#### **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT	
V <sub>CC</sub>	Supply voltage		-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage		-0.5 to +7.0	V
I <sub>IN</sub>	Input current		-30 to +5	mA
V <sub>OUT</sub>	Voltage applied to output in HIGH output state	-0.5 to +V <sub>CC</sub>	V	
1	Current applied to output in LOW output state Q0, Q I/On		40	mA
lout			48	mA
T <sub>amb</sub>	Operating free-air temperature range		0 to +70	°C
T <sub>stg</sub>	Storage temperature		-65 to +150	°C

#### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	LIMITS			UNIT	
			MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage		4.5	5.0	5.5	V
V <sub>IH</sub>	HIGH-level input voltage		2.0			V
V <sub>IL</sub>	LOW-level input voltage				0.8	V
I <sub>IK</sub>	Input clamp current			-18	mA	
		Q0, Q7			-1	mA
ЮН	HIGH-level output current	l/On			-3	mA
	DL LOW-level output current				20	mA
IOL					24	mA
T <sub>amb</sub>	Operating free-air temperature range	0		70	°C	

2003 Feb 05

### 8-bit universal shift/storage register (3-State)

#### **DC ELECTRICAL CHARACTERISTICS**

Over recommended operating free-air temperature range unless otherwise noted.

OVMDO:	DADAMETER					LIMITS			
SYMBOL	- PARAMETER TEST CONDITIONS <sup>1</sup>					MIN	TYP <sup>2</sup>	MAX	UNIT
		00.07		1 1	±10%V <sub>CC</sub>	2.5			V
M		Q0, Q7	$V_{CC} = MIN,$	I <sub>OH</sub> = -1 mA	±5%V <sub>CC</sub>	2.7	3.4		V
V <sub>OH</sub>	HIGH-level output voltage	I/On	V <sub>IL</sub> = MAX, V <sub>IH</sub> = MIN	. 0	±10%V <sub>CC</sub>	2.4			V
		1/On		I <sub>OH</sub> = -3 mA	±5%V <sub>CC</sub>	2.7	3.3		V
M			V <sub>CC</sub> = MIN, ±1	±10%V <sub>CC</sub>		0.35	0.50	V	
V <sub>OL</sub>	LOW-level output voltage		$V_{IL} = MAX,$ $V_{IH} = MIN$	I <sub>OL</sub> = MAX	±5%V <sub>CC</sub>		0.35	0.50	V
V <sub>IK</sub>	Input clamp voltage		V		-0.73	-1.2	V		
l	Input current at maximum	others	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7.0 V					100	μA
	input voltage	l/On	I/On V <sub>CC</sub> = 5.5V, V <sub>I</sub> = 5.5 V				1	mA	
IIH	HIGH-level input current	except I/On	V <sub>C0</sub>	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7 V				20	μA
	LOW level input ourrent	S0, S1	V		= \/			-1.2	mA
ł <sub>IL</sub>	LOW-level input current	others	$V_{CC} = MAX, V_I = 0.5 V$				-0.6	mA	
I <sub>IH +</sub> I <sub>OZH</sub>	Off-state output current, HIGH-level voltage applied	l/On	V <sub>CC</sub>	; = MAX, V <sub>O</sub> = 2.	7 V			70	μA
I <sub>IL +</sub> I <sub>OZL</sub>	Off-state output current LOW-level voltage applied	only	$V_{CC}$ = MAX, $V_O$ = 0.5 V					-0.6	mA
I <sub>OS</sub>	Short-circuit output current <sup>3</sup>		V <sub>CC</sub> = MAX			-60		-150	mA
		I <sub>CCH</sub>					55	60	mA
I <sub>CC</sub>	Supply current (total)	I <sub>CCL</sub>		$V_{CC} = MAX$			70	90	mA
		I <sub>CCZ</sub>						95	mA

#### NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

2. All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_{amb} = 25 \text{ °C}$ . 3. Not more than one output should be shorted at a time. For testing  $I_{OS}$ , the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a HIGH output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

#### **AC ELECTRICAL CHARACTERISTICS**

	PARAMETER			LIMITS					
SYMBOL			TEST CONDITIONS	EST CONDITIONS			$T_{amb}$ = 0 °C to +70 °C V <sub>CC</sub> = +5.0 V ± 10% C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω		UNIT
				MIN	TYP	MAX	MIN	MAX	
4	Maximum clock frequency	I/O	Waveform 1	70	100		70		MHz
f <sub>MAX</sub>	Maximum clock frequency	Qn	wavelonn i	85	115		85		MHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CP to Q0 or Q7		Waveform 1	4.0 4.5	5.0 6.0	7.5 8.0	3.5 4.5	8.5 8.5	ns ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CP to I/On		Waveform 1	4.0 4.0	6.0 6.5	9.0 9.0	4.0 4.0	10.0 10.0	ns ns
t <sub>PHL</sub>	Propagation delay MR to Q0 or Q7		Waveform 2	5.5	7.5	9.5	5.5	10.5	ns
t <sub>PHL</sub>	Propagation delay MR to I/On		Waveform 2	5.5	7.5	10.0	5.5	10.5	ns
t <sub>PZH</sub> t <sub>PZL</sub>	Output Enable time Sn, OE to I/On		Waveform 4 Waveform 5	3.5 4.0	6.0 7.5	8.0 10.0	3.5 4.0	9.0 11.0	ns ns
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output Disable time Sn, OE to I/On	Output Disable time		2.5 1.5	4.5 2.5	7.0 5.5	2.5 1.5	8.0 6.5	ns ns

#### AC SET-UP REQUIREMENTS

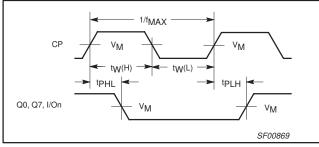
SYMBOL	PARAMETER	TEST CONDITIONS	V	<sub>mb</sub> = +25 ° <sub>CC</sub> = +5.0 0 pF, R <sub>L</sub> =	V	T <sub>amb</sub> = 0 °C V <sub>CC</sub> = +5.0 C <sub>L</sub> = 50 pF,		UNIT
			MIN	TYP	MAX	MIN	MAX	
t <sub>s</sub> (H) t <sub>s</sub> (L)	Set-up time, HIGH or LOW S0 or S1 to CP	Waveform 3	6.5 6.5			7.5 7.5		ns ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time, HIGH or LOW S0 or S1 to CP	Waveform 3	0 0			0 0		ns ns
t <sub>s</sub> (H) t <sub>s</sub> (L)	Set-up time, HIGH or LOW I/On, DS <sub>L</sub> or DS <sub>R</sub> to CP	Waveform 3	3.5 3.5			4.0 4.0		ns ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time, HIGH or LOW I/On, DS <sub>L</sub> or DS <sub>R</sub> to CP	Waveform 3	0 0			0 0		ns ns
t <sub>w</sub> (H) t <sub>w</sub> (L)	CP Pulse width, HIGH or LOW	Waveform 1	5.0 4.5			5.0 4.5		ns
t <sub>w</sub> (L)	MR Pulse width, LOW	Waveform 2	4.5			4.5		ns
t <sub>rec</sub>	Recovery time, MR to CP	Waveform 2	4.0			4.0		ns

### 74F299

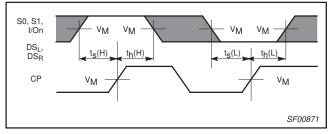
#### AC WAVEFORMS

For all waveforms,  $V_M = 1.5 V$ 

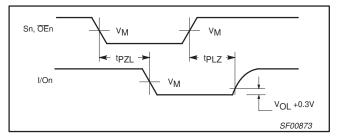
The shaded areas indicate when the input is permitted to change for predictable output performance.



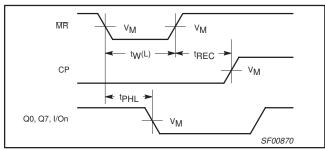
Waveform 1. Propagation delay, clock input to output, clock width, and maximum clock frequency



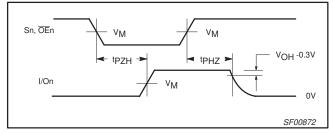
Waveform 3. Set-up and hold times



Waveform 5. 3-State Output Enable time to LOW level and Output Disable time from LOW level

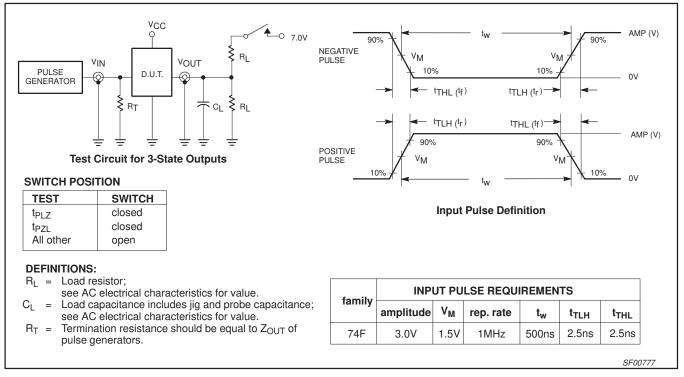


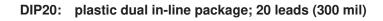
Waveform 2. Master Reset pulse width, Master Reset to output delay, and Master Reset to clock recovery time

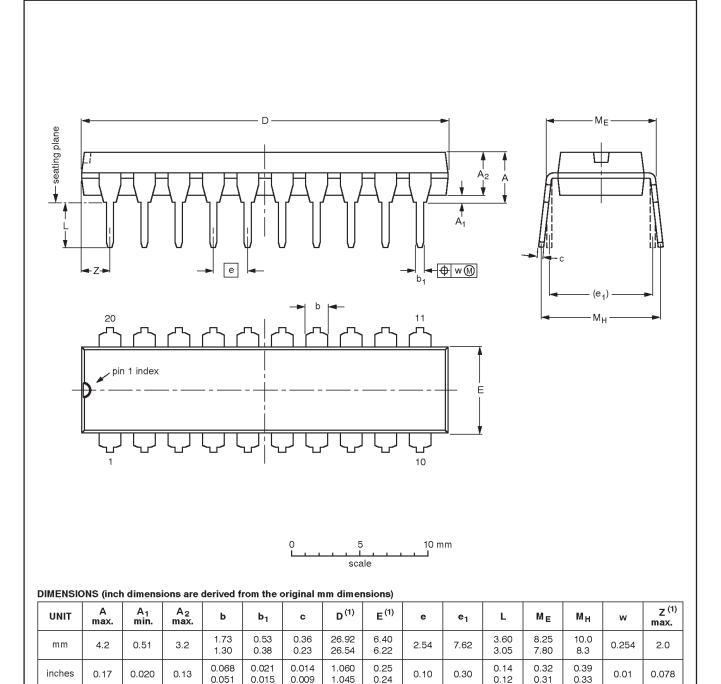


Waveform 4. 3-State Output Enable time to HIGH level and Output Disable time from HIGH level

#### TEST CIRCUIT AND WAVEFORM







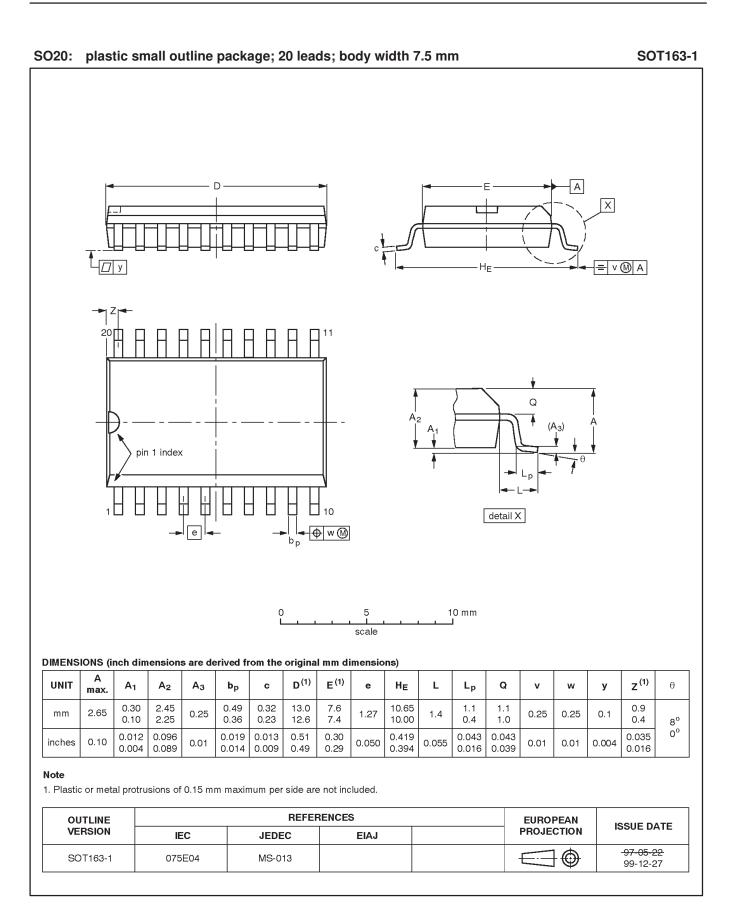
#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		EUROPEAN					
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT146-1		MS-001	SC-603			<del>-95-05-24</del> 99-12-27	

74F299

#### SOT146-1



#### **REVISION HISTORY**

Rev	Date	Description
_3	20030205	Product data (9397 750 11037); ECN 853-0365 29307 of 17 December 2002. Supersedes Product specification (9397 750 05117) of 01 March 1990.
		Modifications:
		<ul> <li>Delete all references to DB package. Package option was discontinued.</li> </ul>
_2	19900301	Product specification (9397 750 05117); ECN 853-0365 29307 of 01 March 1990.

#### Data sheet status

Level	Data sheet status <sup>[1]</sup>	Product status <sup>[2] [3]</sup>	Definitions
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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